Objective: Design and fabricate a pump that is scalable to the micro-domain for liquid pumping and electronics cooling.

Impact: Chip-integration of micro-scale pumping can:
- Increase power dissipation while maintaining small form factor
- Significantly reduce packaging thermal resistance
- Provide flexibility in component constraints and layout

Approach: Enhance induction EHD with fluid motion from a vibrating diaphragm.

Selected Publications: